

|              |   |                     |
|--------------|---|---------------------|
| $V_{DRM}$    | = | 1800 V              |
| $I_{T(AV)M}$ | = | 2940 A              |
| $I_{T(RMS)}$ | = | 4620 A              |
| $I_{TSM}$    | = | $50.5 \cdot 10^3$ A |
| $V_{T0}$     | = | 0.912 V             |
| $r_T$        | = | 0.096 m $\Omega$    |

# Phase Control Thyristor

## 5STP 27H1800

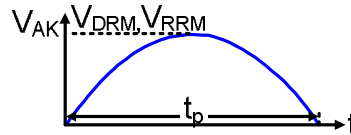
Doc. No. 5SYA1048-04 May. 20

- Patented free-floating silicon technology
- Low on-state and switching losses
- Designed for traction, energy and industrial applications
- Optimum power handling capability

### Blocking

Maximum rated values <sup>1)</sup>

| Parameter  | Symbol             | Conditions   | 5STP 27H1800 | Unit       |
|--|--------------------|--|--------------|------------|
| Max repetitive peak forward and reverse blocking voltage | $V_{DRM}, V_{RRM}$ | $f = 50$ Hz, $t_p = 10$ ms,<br>$T_{vj} = 5 \dots 125$ °C, Note 1 | 1800         | V          |
| Critical rate of rise of commutating voltage             | $dv/dt_{crit}$     | Exp. to $0.67 \cdot V_{DRM}$ , $T_{vj} = 125$ °C                 | 1000         | V/ $\mu$ s |



Characteristic values

| Parameter               | Symbol    | Conditions                    | min | typ | max | Unit |
|-------------------------|-----------|-------------------------------|-----|-----|-----|------|
| Forward leakage current | $I_{DRM}$ | $V_{DRM}$ , $T_{vj} = 125$ °C |     |     | 200 | mA   |
| Reverse leakage current | $I_{RRM}$ | $V_{RRM}$ , $T_{vj} = 125$ °C |     |     | 200 | mA   |

Note 1: Voltage de-rating factor of 0.11% per °C is applicable for  $T_{vj}$  below +5 °C.

### Mechanical data

Maximum rated values <sup>1)</sup>

| Parameter      | Symbol | Conditions       | min | typ | max | Unit             |
|----------------|--------|------------------|-----|-----|-----|------------------|
| Mounting force | $F_M$  |                  | 45  | 50  | 60  | kN               |
| Acceleration   | $a$    | Device unclamped |     |     | 50  | m/s <sup>2</sup> |
| Acceleration   | $a$    | Device clamped   |     |     | 100 | m/s <sup>2</sup> |

Characteristic values

| Parameter                 | Symbol | Conditions                   | min   | typ | max   | Unit |
|---------------------------|--------|------------------------------|-------|-----|-------|------|
| Weight                    | $m$    |                              |       |     | 0.9   | kg   |
| Housing thickness         | $H$    | $F_M = 50$ kN, $T_a = 25$ °C | 25.62 |     | 26.27 | mm   |
| Surface creepage distance | $D_s$  |                              | 36    |     |       | mm   |
| Air strike distance       | $D_a$  |                              | 15    |     |       | mm   |

1) Maximum rated values indicate limits beyond which damage to the device may occur

ABB Power Grids Switzerland Ltd, Semiconductors reserves the right to change specifications without notice.



## On-state

### Maximum rated values <sup>1)</sup>

| Parameter                         | Symbol       | Conditions  | min | typ | max               | Unit   |
|-----------------------------------|--------------|---|-----|-----|-------------------|--------|
| Average on-state current          | $I_{T(AV)M}$ | Half sine wave, $T_c = 70\text{ °C}$  |     |     | 2940              | A      |
| RMS on-state current              | $I_{T(RMS)}$ |   |     |     | 4620              | A      |
| Peak non-repetitive surge current | $I_{TSM}$    | $t_p = 10\text{ ms}$ , $T_{vj} = 125\text{ °C}$ ,<br>sine half wave,<br>$V_D = V_R = 0\text{ V}$ , after surge  |     |     | $50.5 \cdot 10^3$ | A      |
| Limiting load integral            | $I^2t$       |   |     |     | $12.8 \cdot 10^6$ | $A^2s$ |
| Peak non-repetitive surge current | $I_{TSM}$    | $t_p = 10\text{ ms}$ , $T_{vj} = 125\text{ °C}$ ,<br>sine half wave,<br>$V_R = 0.6 \cdot V_{RRM}$ , after surge |     |     |                   | A      |
| Limiting load integral            | $I^2t$       |   |     |     |                   | $A^2s$ |

### Characteristic values

| Parameter         | Symbol     | Conditions   | min | typ  | max   | Unit      |
|-------------------|------------|--|-----|------|-------|-----------|
| On-state voltage  | $V_T$      | $I_T = 3000\text{ A}$ , $T_{vj} = 125\text{ °C}$                 |     | 1.12 | 1.20  | V         |
| Threshold voltage | $V_{(TO)}$ | $I_T = 2000\text{ A} - 6000\text{ A}$ , $T_{vj} = 125\text{ °C}$ |     |      | 0.912 | V         |
| Slope resistance  | $r_T$      |  |     |      | 0.096 | $m\Omega$ |
| Holding current   | $I_H$      | $T_{vj} = 25\text{ °C}$  |     |      | 70    | mA        |
|                   |            | $T_{vj} = 125\text{ °C}$   |     |      | 60    | mA        |
| Latching current  | $I_L$      | $T_{vj} = 25\text{ °C}$  |     |      | 600   | mA        |
|                   |            | $T_{vj} = 125\text{ °C}$   |     |      | 200   | mA        |

## Switching

### Maximum rated values <sup>1)</sup>

| Parameter                                 | Symbol         | Conditions  | min | typ | max  | Unit      |
|---|----------------|---|-----|-----|------|-----------|
| Critical rate of rise of on-state current | $di/dt_{crit}$ | $T_{vj} = 125\text{ °C}$ ,<br>$I_T = 3000\text{ A}$ ,<br>$V_D \leq 0.67 \cdot V_{DRM}$ ,<br>$I_{GM} = 2\text{ A}$ , $t_r = 0.5\text{ }\mu s$                                  |     |     | 150  | $A/\mu s$ |
|   |                | Cont.<br>$f = 50\text{ Hz}$   |     |     | 1000 | $A/\mu s$ |
| Circuit-commutated turn-off time          | $t_q$          | $T_{vj} = 125\text{ °C}$ , $I_T = 2000\text{ A}$ ,<br>$V_R = 200\text{ V}$ , $di/dt = -1.5\text{ A}/\mu s$ ,<br>$V_D \leq 0.67 \cdot V_{DRM}$ , $dV_D/dt = 20\text{ V}/\mu s$ |     |     | 400  | $\mu s$   |

### Characteristic values

| Parameter                | Symbol   | Conditions   | min | typ | max  | Unit     |
|--------------------------|----------|--|-----|-----|------|----------|
| Reverse recovery charge  | $Q_{rr}$ | $T_{vj} = 125\text{ °C}$ , $I_T = 2000\text{ A}$ ,<br>$V_R = 200\text{ V}$ , $di/dt = -1.5\text{ A}/\mu s$ | 400 | 800 | 1000 | $\mu As$ |
| Reverse recovery current | $I_{RM}$ |  | 15  | 31  | 40   | A        |
| Gate turn-on delay time  | $t_{gd}$ | $T_{vj} = 25\text{ °C}$ , $V_D = 0.4 \cdot V_{RM}$ ,<br>$I_{GM} = 2\text{ A}$ , $t_r = 0.5\text{ }\mu s$   |     |     | 3    | $\mu s$  |

### Triggering

Maximum rated values <sup>1)</sup>

| Parameter                 | Symbol             | Conditions | min        | typ | max | Unit |
|---------------------------|--------------------|------------|------------|-----|-----|------|
| Peak forward gate voltage | V <sub>FGM</sub>   |            |            |     | 12  | V    |
| Peak forward gate current | I <sub>FGM</sub>   |            |            |     | 10  | A    |
| Peak reverse gate voltage | V <sub>RGM</sub>   |            |            |     | 10  | V    |
| Average gate power loss   | P <sub>G(AV)</sub> |            | see Fig. 7 |     |     | W    |

Characteristic values

| Parameter                | Symbol          | Conditions  | min | typ | max | Unit |
|--------------------------|-----------------|---|-----|-----|-----|------|
| Gate-trigger voltage     | V <sub>GT</sub> | T <sub>vj</sub> = 25 °C   |     |     | 2.6 | V    |
| Gate-trigger current     | I <sub>GT</sub> | T <sub>vj</sub> = 25 °C   |     |     | 400 | mA   |
| Gate non-trigger voltage | V <sub>GD</sub> | V <sub>D</sub> = 0.4·V <sub>DRM</sub> , T <sub>vjmax</sub> = 125 °C |     |     | 0.3 | V    |
| Gate non-trigger current | I <sub>GD</sub> | V <sub>D</sub> = 0.4·V <sub>DRM</sub> , T <sub>vjmax</sub> = 125 °C |     |     | 10  | mA   |

### Thermal

Maximum rated values <sup>1)</sup>

| Parameter                            | Symbol           | Conditions | min | typ | max | Unit |
|--------------------------------------|------------------|------------|-----|-----|-----|------|
| Operating junction temperature range | T <sub>vj</sub>  |            |     |     | 125 | °C   |
| Storage temperature range            | T <sub>stg</sub> |            | -40 |     | 140 | °C   |

Characteristic values

| Parameter                           | Symbol                | Conditions  | min | typ | max | Unit |
|-------------------------------------|-----------------------|---|-----|-----|-----|------|
| Thermal resistance junction to case | R <sub>th(j-c)</sub>  | Double-side cooled<br>F <sub>m</sub> = 45... 60 kN  |     |     | 10  | K/kW |
|                                     | R <sub>th(j-c)A</sub> | Anode-side cooled<br>F <sub>m</sub> = 45... 60 kN   |     |     | 20  | K/kW |
|                                     | R <sub>th(j-c)C</sub> | Cathode-side cooled<br>F <sub>m</sub> = 45... 60 kN |     |     | 20  | K/kW |
| Thermal resistance case to heatsink | R <sub>th(c-h)</sub>  | Double-side cooled<br>F <sub>m</sub> = 45... 60 kN  |     |     | 2   | K/kW |
|                                     | R <sub>th(c-h)</sub>  | Single-side cooled<br>F <sub>m</sub> = 45... 60 kN  |     |     | 4   | K/kW |

Analytical function for transient thermal impedance:

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

| i                     | 1      | 2      | 3      | 4      |
|-----------------------|--------|--------|--------|--------|
| R <sub>i</sub> (K/kW) | 6.722  | 2.157  | 1.019  | 0.102  |
| τ <sub>i</sub> (s)    | 0.4544 | 0.0429 | 0.0026 | 0.0004 |

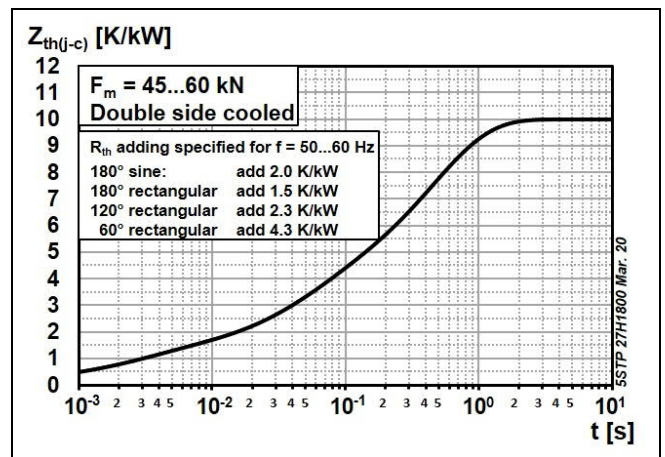


Fig. 1 Transient thermal impedance (junction-to-case) vs. time

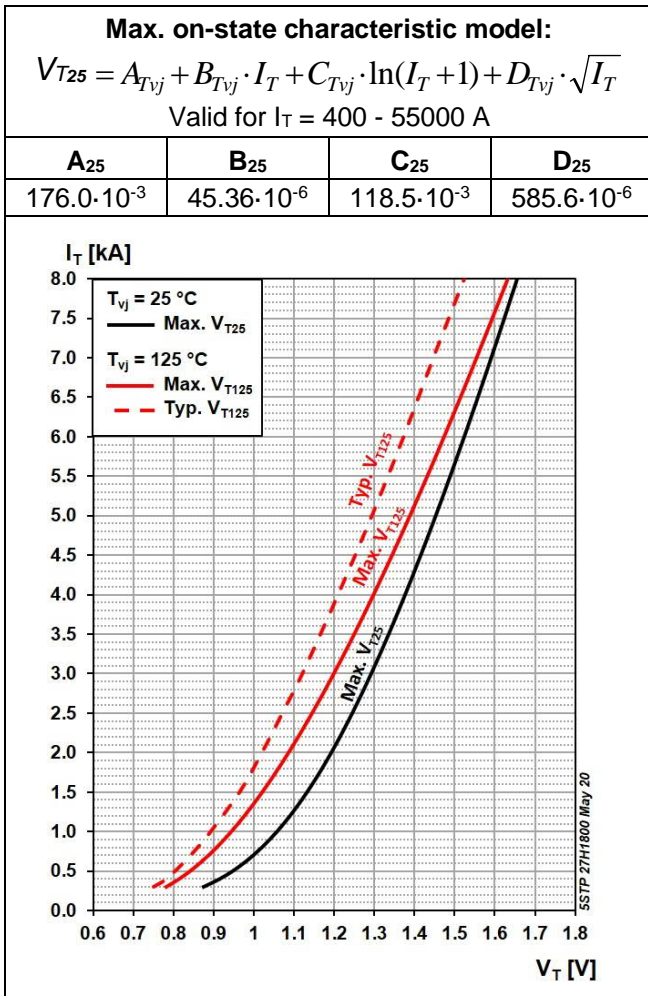


Fig. 2 On-state voltage characteristics

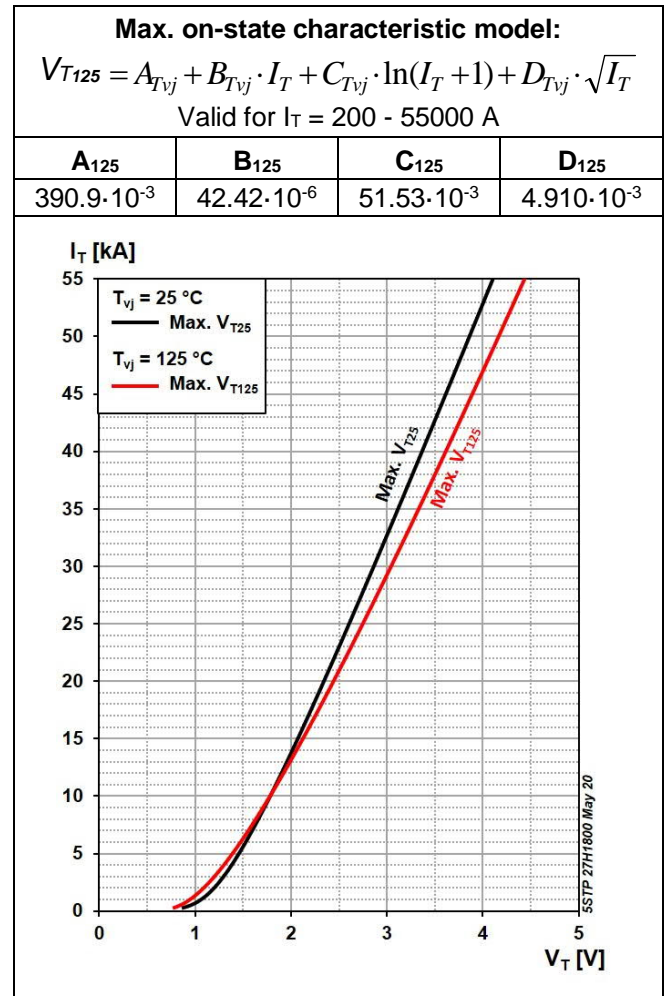


Fig. 3 On-state voltage characteristics

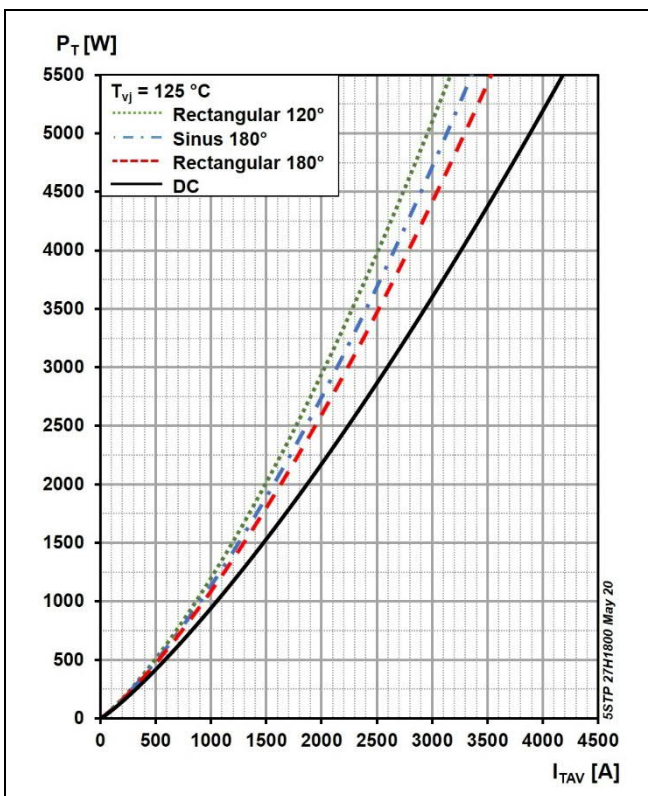


Fig. 4 On-state power dissipation vs. mean on-state current, turn-on losses excluded

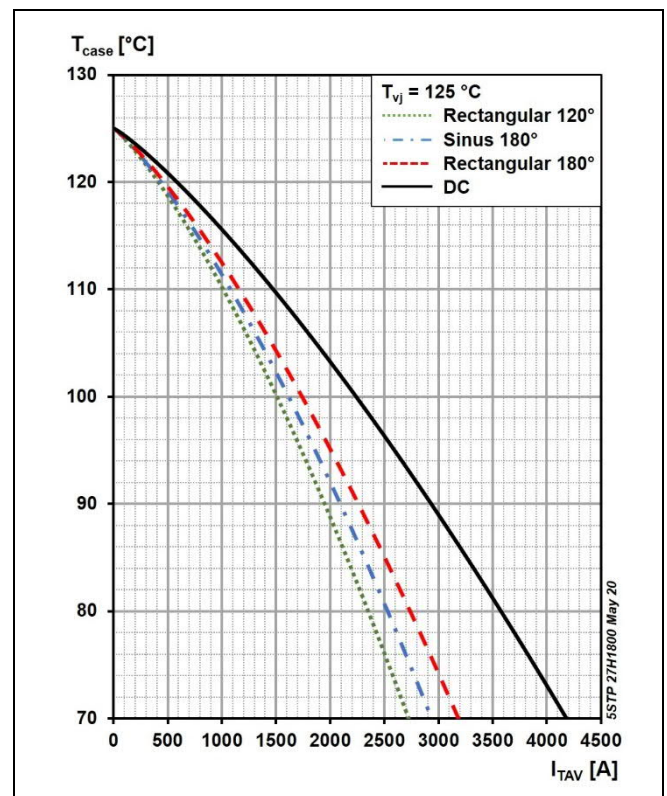


Fig. 5 Max. permissible case temperature vs. mean on-state current, switching losses ignored



Fig. 6 Recommended gate current waveform

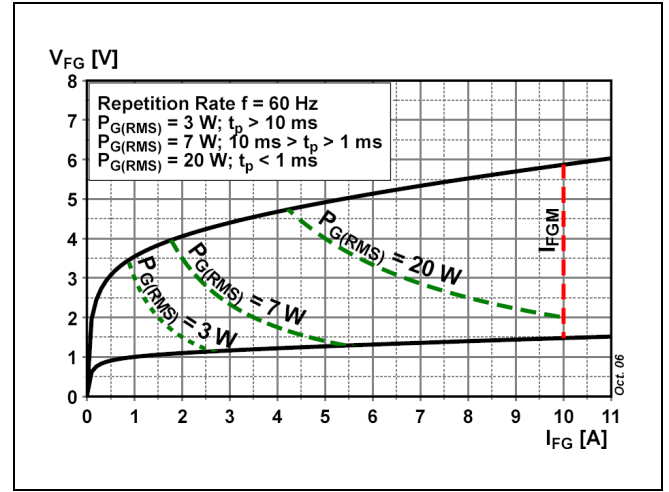


Fig. 7 Max. peak gate power loss

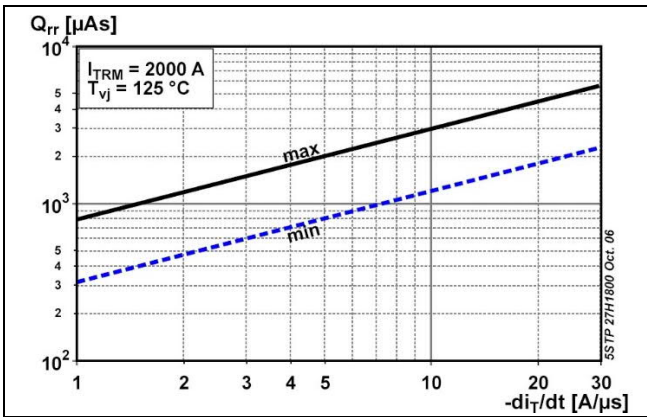


Fig. 8 Reverse recovery charge vs. decay rate of on-state current

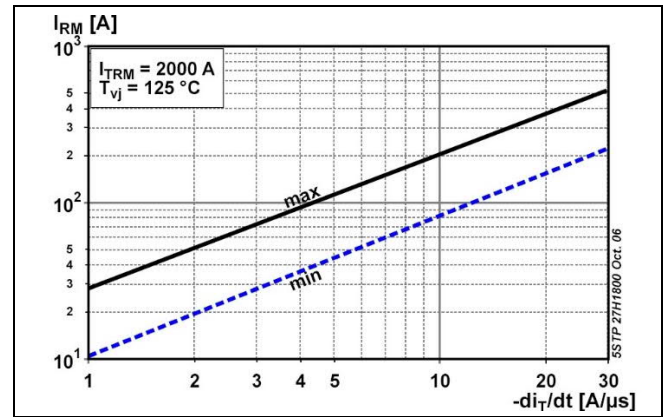


Fig. 9 Peak reverse recovery current vs. decay rate of on-state current

# Turn-on and Turn-off losses

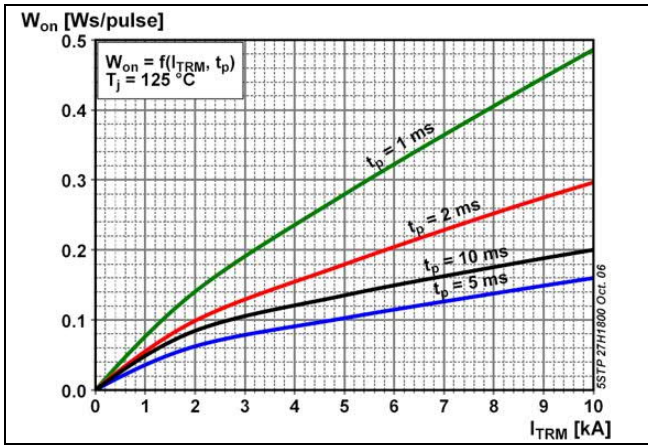


Fig. 10 Turn-on energy, half sinusoidal waves

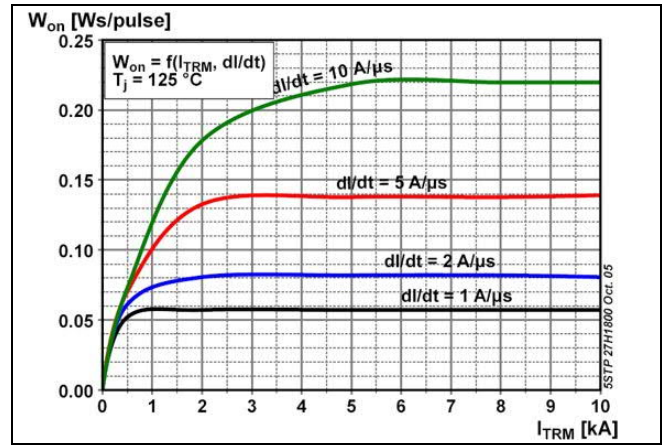


Fig. 11 Turn-on energy, rectangular waves

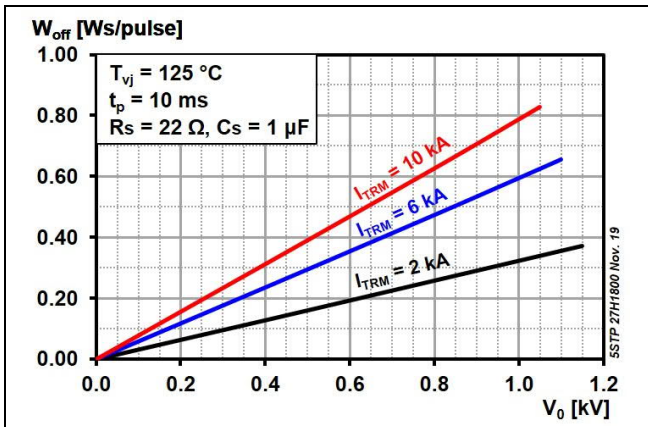


Fig. 12 Typical turn-off energy, half sinusoidal waves

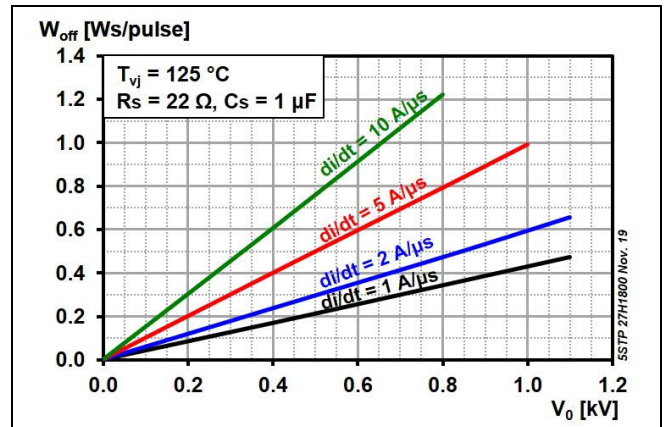


Fig. 13 Typical turn-off energy, rectangular waves

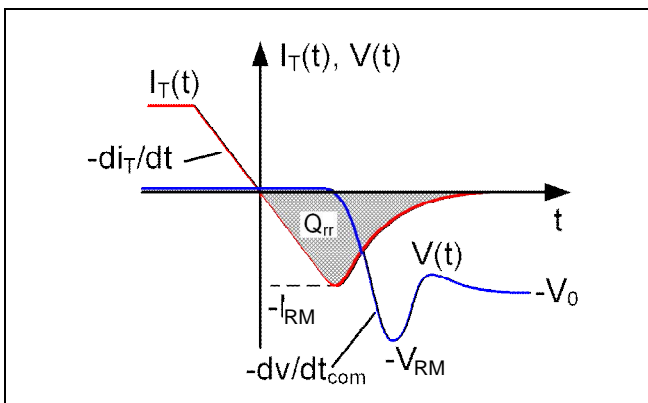


Fig. 14 Current and voltage waveforms at turn-off

**Total power loss for repetitive waveforms:**

$$P_{TOT} = P_T + W_{on} \cdot f + W_{off} \cdot f$$

where

$$P_T = \frac{1}{T} \int_0^T I_T \cdot V_T(I_T) dt$$

Fig. 15 Relationships for power loss

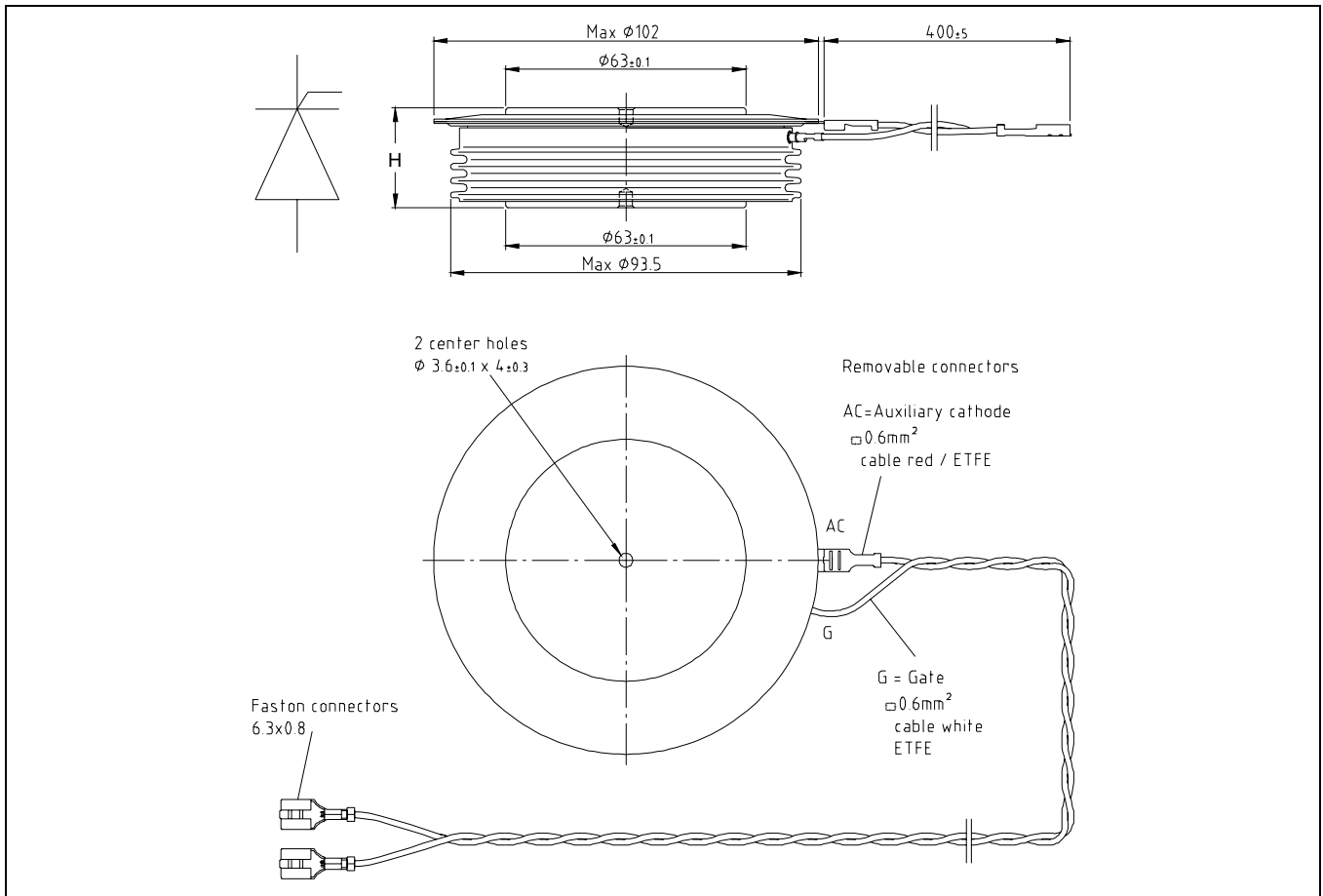


Fig. 16 Device Outline Drawing

### Related documents:

|           |   |
|-----------|---|
| 5SYA 2020 | Design of RC-Snubbers for Phase Control Applications                                    |
| 5SYA 2049 | Voltage definitions for phase control and bi-directionally controlled thyristors        |
| 5SYA 2051 | Voltage ratings of high power semiconductors  |
| 5SYA 2034 | Gate-drive recommendations for phase control and bi-directionally controlled thyristors |
| 5SYA 2036 | Recommendations regarding mechanical clamping of Press-Pack High Power Semiconductors   |
| 5SZK 9118 | General Environmental Conditions for High Power Semiconductors                          |

Please refer to <http://www.abb.com/semiconductors> for current version of documents.

ABB Power Grids Switzerland Ltd, Semiconductors reserves the right to change specifications without notice.

# ABB

**ABB Power Grids Switzerland Ltd**  
**Semiconductors**  
 Fabrikstrasse 3  
 CH-5600 Lenzburg, Switzerland

Doc. No. 5SYA1048-04 May. 20

Telephone +41 (0)58 586 1419  
 Fax +41 (0)58 586 1306  
 Email [abbsem@ch.abb.com](mailto:abbsem@ch.abb.com)  
 Internet [www.abb.com/semiconductors](http://www.abb.com/semiconductors)